Z21 □ Install label in silk-screened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
Z22 □ These assemblies are ESD sensitive, ESD precautions shall be observed.
Z23 □ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
Z24 □ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

components marked 'DNP' should not be populated.
assembly variant: 001

Pcb viewed from Top side
layer name = M5 Assembly Top
plot name = Top Assembly Drawing

board #: TIDA-01592
rev.: E1
sun rev: not in version control

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